DATA SHEET

74LVC07A
Hex buffer with open-drain outputs

Product specification
Supersedes data of 2003 Feb 25

2003 Nov 11

Philips
Semiconductors

Hex buffer with open-drain outputs 74LVC07A

FEATURES

- 5 V tolerant inputs and outputs (open drain) for interfacing with 5 V logic
- Wide supply voltage range from 1.65 to 5.5 V
- CMOS low power consumption
- Direct interface with TTL levels
- Inputs accept voltages up to 5 V
- Complies with JEDEC standard no. 8-1A
- ESD protection:
  HBM EIA/JESD22-A114-A exceeds 2000 V
  MM EIA/JESD22-A115-A exceeds 200 V.

DESCRIPTION

The 74LVC07A is a high-performance, low-power, low-voltage, Si-gate CMOS device, superior to most advanced CMOS compatible TTL families. Inputs can be driven from either 3.3 or 5 V devices. This feature allows the use of these devices as translators in a mixed 3.3 to 5 V environment.

The 74LVC07A provides six non-inverting buffers.

The outputs of the 74LVC07A are open drain and can be connected to other open-drain outputs to implement active-LOW wired-OR or active-HIGH wired-AND functions.

QUICK REFERENCE DATA

GND = 0 V; T_{amb} = 25 °C; $t_r = t_f \leq 2.5$ ns.

SYMBOL	PARAMETER	CONDITIONS	TYPICAL	UNIT
t_{PLZ}/t_{PZL}	propagation delay nA to nY	C_L = 50 pF; V_{CC} = 3.3 V	2.2	ns
C_I	input capacitance		5.0	pF
C_{PD}	power dissipation capacitance per gate	V_{CC} = 3.3 V; notes 1 and 2	6.0	pF

Note

1. C_{PD} is used to determine the dynamic power dissipation (P_D in µW).
   $P_D = C_{PD} \times V_{CC}^2 \times f_i \times N + \Sigma(C_L \times V_{CC}^2 \times f_o)$ where:
   f_i = input frequency in MHz;
   f_o = output frequency in MHz;
   C_L = output load capacitance in pF;
   V_{CC} = supply voltage in Volts;
   N = total load switching outputs;
   $\Sigma(C_L \times V_{CC}^2 \times f_o)$ = sum of the outputs.
2. The condition is V_I = GND to V_{CC}

FUNCTION TABLE

See note 1.

INPUT	OUTPUT
nA	**nY**
L	L
H	Z

Note

1. H = HIGH voltage level;
   L = LOW voltage level;
   Z = high-impedance OFF-state.

ORDERING INFORMATION

TYPE NUMBER	PACKAGE				
	TEMPERATURE RANGE	PINS	PACKAGE	MATERIAL	CODE
74LVC07AD	–40 to +125 °C	14	SO14	plastic	SOT108-1
74LVC07APW	–40 to +125 °C	14	TSSOP14	plastic	SOT402-1
74LVC07ABQ	–40 to +125 °C	14	DHVQFN14	plastic	SOT762-1

PINNING

PIN	SYMBOL	DESCRIPTION
1	1A	data input
2	1Y	data output
3	2A	data input
4	2Y	data output
5	3A	data input
6	3Y	data output
7	GND	ground (0 V)
8	4Y	data output
9	4A	data input
10	5Y	data output
11	5A	data input
12	6Y	data output
13	6A	data input
14	V_{CC}	supply voltage

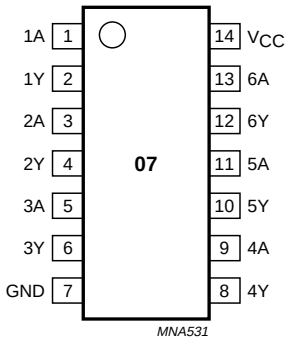
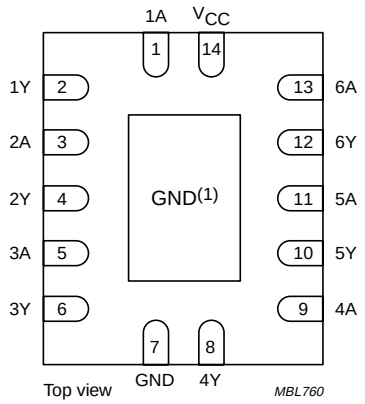


Fig.1 Pin configuration SO14 and TSSOP14.



(1) The die substrate is attached to this pad using conductive die attach material. It can not be used as a supply pin or input.

Fig.2 Pin configuration DHVQFN14.

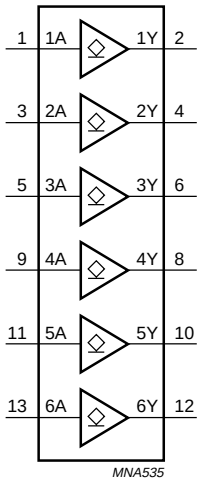


Fig.3 Logic symbol.

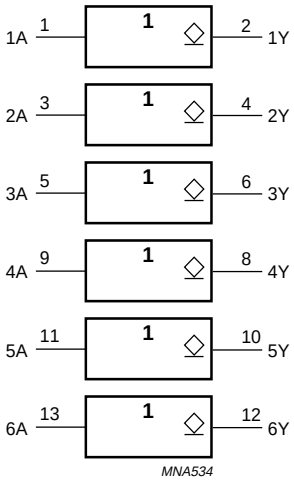


Fig.4 IEC logic symbol.

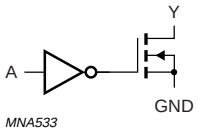


Fig.5 Logic diagram (one gate).

RECOMMENDED OPERATING CONDITIONS

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		1.65	5.5	V
V_I	input voltage		0	5.5	V
V_O	output voltage	active mode	0	5.5	V
		high-impedance mode	0	5.5	V
T_{amb}	operating ambient temperature		–40	+125	°C
t_r, t_f	input rise and fall ratios	V_{CC} = 1.65 to 2.7 V	0	20	ns/V
		V_{CC} = 2.7 to 5.5 V	0	10	ns/V

LIMITING VALUES

In accordance with the Absolute Maximum Rating System (IEC 60134); voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V_{CC}	supply voltage		–0.5	+6.5	V
I_{IK}	input diode current	$V_I < 0$	–	–50	mA
V_I	input voltage	note 1	–0.5	+6.5	V
I_{OK}	output clamping diode current	$V_O < 0$	–	–50	mA
V_O	output voltage	active mode; note 1	–0.5	+6.5	V
		high-impedance mode; note 1	–0.5	+6.5	V
I_O	output source or sink current	V_O = 0 to V_{CC}	–	50	mA
I_{CC}, I_{GND}	V_{CC} or GND current		–	±100	mA
T_{stg}	storage temperature		–65	+150	°C
P_{tot}	power dissipation	T_{amb} = –40 to +125 °C; note 2	–	500	mW

Notes

1. The input and output voltage ratings may be exceeded if the input and output current ratings are observed.
2. For SO14 packages: above 70 °C derate linearly with 8 mW/K.
   For TSSOP14 packages: above 60 °C derate linearly with 5.5 mW/K.
   For DHVQFN14 packages: above 60 °C derate linearly with 4.5 mW/K.

DC CHARACTERISTICS

At recommended operating conditions; voltages are referenced to GND (ground = 0 V).

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V_{CC} (V)				
T_{amb} = −40 to +85 °C; note 1							
V_{IH}	HIGH-level input voltage		1.65 to 1.95	V_{CC}	–	–	V
			2.3 to 2.7	1.7	–	–	V
			2.7 to 3.6	2.0	–	–	V
			4.5 to 5.5	$0.7 \times V_{CC}$	–	–	V
V_{IL}	LOW-level input voltage		1.65 to 1.95	–	–	GND	V
			2.3 to 2.7	–	–	0.7	V
			2.7 to 3.6	–	–	0.8	V
			4.5 to 5.5	–	–	$0.30 \times V_{CC}$	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		I_O = 100 µA	1.65 to 5.5	–	–	0.20	V
		I_O = 4 mA	1.65	–	–	0.45	V
		I_O = 8 mA	2.3	–	–	0.3	V
		I_O = 12 mA	2.7	–	–	0.4	V
		I_O = 24 mA	3.0	–	–	0.55	V
		I_O = 32 mA	4.5	–	–	0.55	V
I_{LI}	input leakage current	V_I = 5.5 V or GND	1.65 to 5.5	–	±0.1	±5	µA
I_{OZ}	output leakage current	$V_I = V_{IH}$; V_O = 5.5 V or GND	1.65 to 5.5	–	0.1	±10	µA
I_{off}	power-off leakage current	V_I or V_O = 5.5 V	0.0	–	±0.1	±10	µA
I_{CC}	quiescent supply current	$V_I = V_{CC}$ or GND; I_O = 0	5.5	–	0.1	10	µA
ΔI_{CC}	additional quiescent supply current per input pin	$V_I = V_{CC}$ − 0.6 V; I_O = 0	2.3 to 5.5	–	5	500	µA

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		OTHER	V_{CC} (V)				
T_{amb} = −40 to +125 °C							
V_{IH}	HIGH-level input voltage		1.65 to 1.95	V_{CC}	–	–	V
			2.3 to 2.7	1.7	–	–	V
			2.7 to 3.6	2.0	–	–	V
			4.5 to 5.5	$0.7 \times V_{CC}$	–	–	V
V_{IL}	LOW-level input voltage		1.65 to 1.95	–	–	GND	V
			2.3 to 2.7	–	–	0.7	V
			2.7 to 3.6	–	–	0.8	V
			4.5 to 5.5	–	–	$0.30 \times V_{CC}$	V
V_{OL}	LOW-level output voltage	$V_I = V_{IH}$ or V_{IL}					
		I_O = 100 μA	1.65 to 5.5	–	–	0.20	V
		I_O = 4 mA	1.65	–	–	0.45	V
		I_O = 8 mA	2.3	–	–	0.3	V
		I_O = 12 mA	2.7	–	–	0.4	V
		I_O = 24 mA	3.0	–	–	0.55	V
		I_O = 32 mA	4.5	–	–	0.55	V
I_{LI}	input leakage current	V_I = 5.5 V or GND	1.65 to 5.5	–	–	±5	μA
I_{OZ}	output leakage current	$V_I = V_{IH}$; V_O = 5.5 V or GND	1.65 to 5.5	–	–	±10	μA
I_{off}	power-off leakage current	V_I or V_O = 5.5 V	0.0	–	–	±10	μA
I_{CC}	quiescent supply current	$V_I = V_{CC}$ or GND; I_O = 0	5.5	–	–	10	μA
ΔI_{CC}	additional quiescent supply current per input pin	$V_I = V_{CC}$ – 0.6 V; I_O = 0	2.3 to 5.5	–	–	500	μA

Note

1. All typical values are measured at V_{CC} = 3.3 V and T_{amb} = 25 °C.

AC CHARACTERISTICS

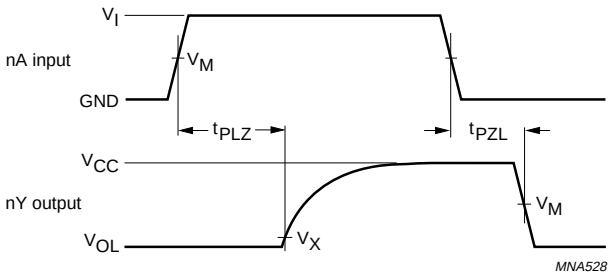
GND = 0 V; $t_r = t_f \leq 2$ ns for $V_{CC} \leq 2.7$ V and $t_r = t_f \leq 2.5$ ns for $V_{CC} \geq 2.7$ V.

SYMBOL	PARAMETER	TEST CONDITIONS		MIN.	TYP.	MAX.	UNIT
		WAVEFORMS	V_{CC} (V)				
T_{amb} = −40 to +85 °C; note 1							
t_{PLZ}/t_{PZL}	propagation delay nA to nY	see Figs 6 and 7	1.65 to 1.95	–	2.5	–	ns
			2.3 to 2.7	0.5	1.6	2.8	ns
			2.7	0.5	2.4	3.3	ns
			3.0 to 3.6	0.5	2.2	3.6	ns
			4.5 to 5.5	0.5	1.6	2.6	ns
T_{amb} = −40 to +125 °C							
t_{PLZ}/t_{PZL}	propagation delay nA to nY	see Figs 6 and 7	1.65 to 1.95	–	–	–	ns
			2.3 to 2.7	0.5	–	3.5	ns
			2.7	0.5	–	4.5	ns
			3.0 to 3.6	0.5	–	4.5	ns
			4.5 to 5.5	0.5	–	3.5	ns

Note

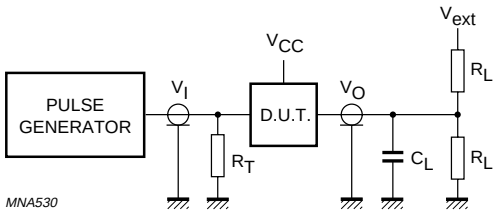
1. All typical values are measured at T_{amb} = 25 °C and at V_{CC} = 1.8, 2.5, 2.7, 3.3 and 5.0 V, respectively.

AC WAVEFORMS



V_{CC}	V_M	V_X
<2.7 V	$0.5 \times V_{CC}$	V_{OL} + 0.15 V
≥2.7 to 3.6 V	1.5 V	V_{OL} + 0.3 V
≥4.5 to 5.5 V	$0.5 \times V_{CC}$	V_{OL} + 0.3 V

Fig.6 The input nA to output nY propagation delays.



V_{CC}	V_{ext}	V_I	C_L	R_L
1.65 to 1.95 V	$2 \times V_{CC}$	V_{CC}	30 pF	1 kΩ
2.3 to 2.7 V	$2 \times V_{CC}$	V_{CC}	30 pF	500 Ω
2.7 V	6 V	2.7 V	50 pF	500 Ω
3.0 to 3.6 V	6 V	2.7 V	50 pF	500 Ω
4.5 to 5.5 V	$2 \times V_{CC}$	V_{CC}	50 pF	500 Ω

Definitions for test circuits:

R_L = Load resistor.

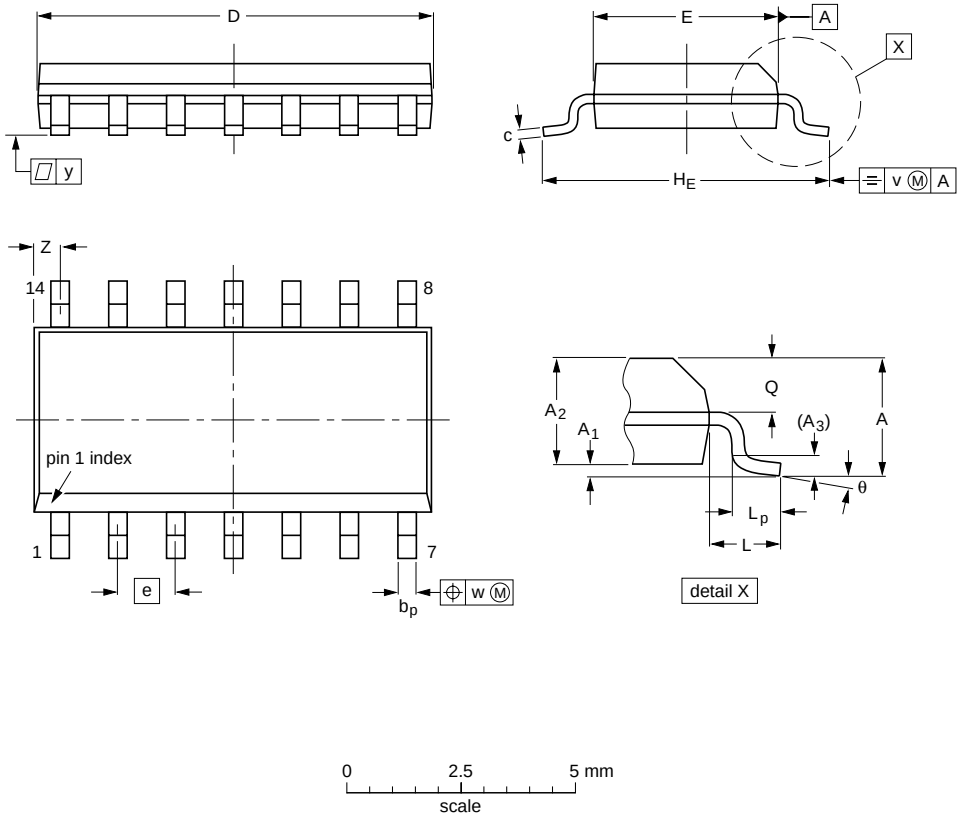
C_L = Load capacitance including jig and probe capacitance.

R_T = Termination resistance should be equal to the output impedance Z_o of the pulse generator.

Fig.7 Load circuitry for switching times.

PACKAGE OUTLINES

SO14: plastic small outline package; 14 leads; body width 3.9 mm **SOT108-1**



DIMENSIONS (inch dimensions are derived from the original mm dimensions)

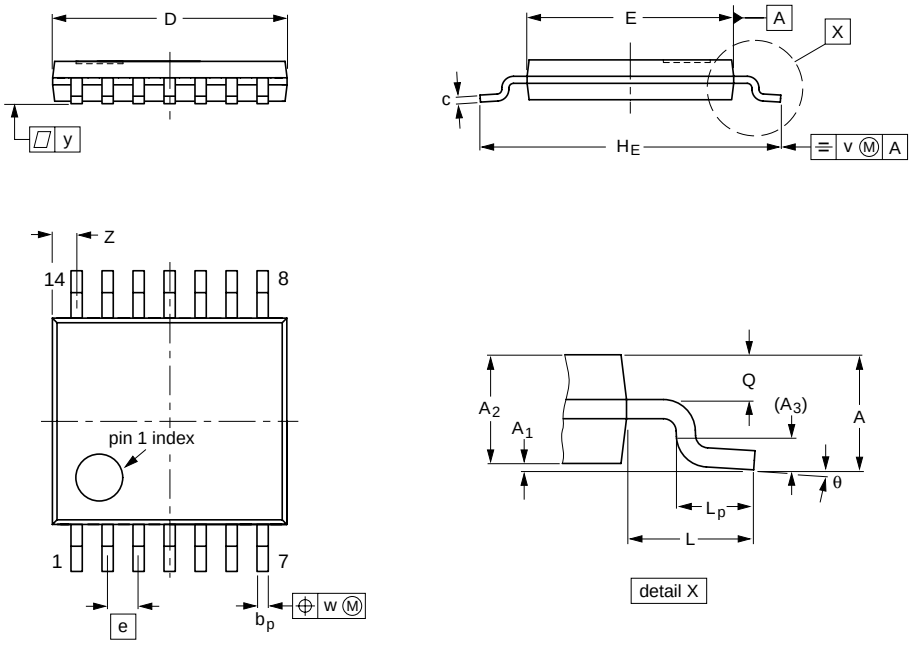
UNIT	A max.	A_1	A_2	A_3	b_p	c	$D^{(1)}$	$E^{(1)}$	e	H_E	L	L_p	Q	v	w	y	$Z^{(1)}$	θ
mm	1.75	0.25 0.10	1.45 1.25	0.25	0.49 0.36	0.25 0.19	8.75 8.55	4.0 3.8	1.27	6.2 5.8	1.05	1.0 0.4	0.7 0.6	0.25	0.25	0.1	0.7 0.3	8^o 0^o
inches	0.069	0.010 0.004	0.057 0.049	0.01	0.019 0.014	0.0100 0.0075	0.35 0.34	0.16 0.15	0.05	0.244 0.228	0.041	0.039 0.016	0.028 0.024	0.01	0.01	0.004	0.028 0.012	

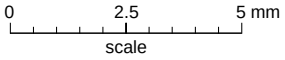
Note

1. Plastic or metal protrusions of 0.15 mm (0.006 inch) maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT108-1	076E06	MS-012				~~99-12-27~~ 03-02-19

TSSOP14: plastic thin shrink small outline package; 14 leads; body width 4.4 mm **SOT402-1**





DIMENSIONS (mm are the original dimensions)

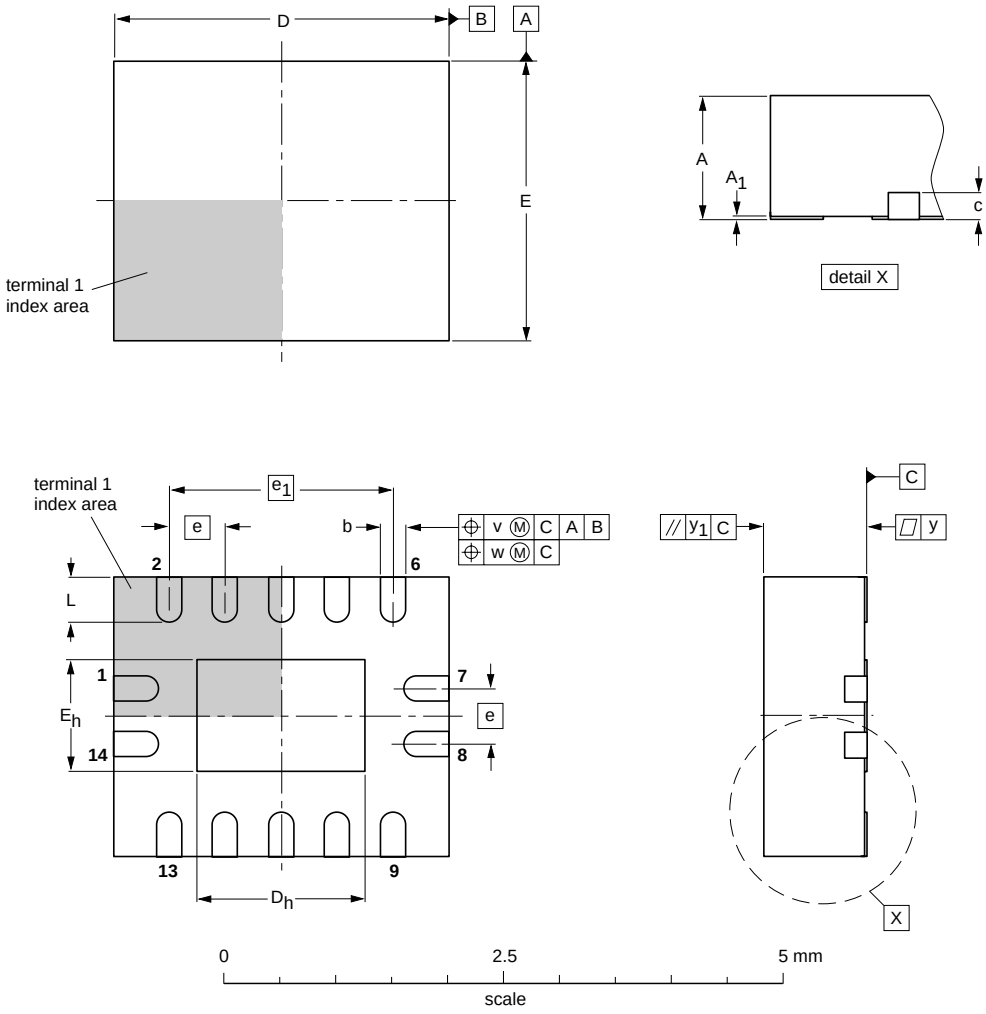
UNIT	A max.	A_1	A_2	A_3	b_p	c	D (1)	E (2)	e	H_E	L	L_p	Q	v	w	y	Z (1)	θ
mm	1.1	0.15 0.05	0.95 0.80	0.25	0.30 0.19	0.2 0.1	5.1 4.9	4.5 4.3	0.65	6.6 6.2	1	0.75 0.50	0.4 0.3	0.2	0.13	0.1	0.72 0.38	8^o 0^o

Notes

1. Plastic or metal protrusions of 0.15 mm maximum per side are not included.
2. Plastic interlead protrusions of 0.25 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT402-1		MO-153				~~99-12-27~~ 03-02-18

DHVQFN14: plastic dual in-line compatible thermal enhanced very thin quad flat package; no leads; 14 terminals; body 2.5 x 3 x 0.85 mm **SOT762-1**



DIMENSIONS (mm are the original dimensions)

UNIT	$A^{(1)}$ max.	A_1	b	c	$D^{(1)}$	D_h	$E^{(1)}$	E_h	e	e_1	L	v	w	y	y_1
mm	1	0.05 0.00	0.30 0.18	0.2	3.1 2.9	1.65 1.35	2.6 2.4	1.15 0.85	0.5	2	0.5 0.3	0.1	0.05	0.05	0.1

Note

1. Plastic or metal protrusions of 0.075 mm maximum per side are not included.

OUTLINE VERSION	REFERENCES				EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA			
SOT762-1	- - -	MO-241	- - -			~~02-10-17~~ 03-01-27

DATA SHEET STATUS

LEVEL	DATA SHEET STATUS[1]	PRODUCT STATUS[2][3]	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
II	Preliminary data	Qualification	This data sheet contains data from the preliminary specification. Supplementary data will be published at a later date. Philips Semiconductors reserves the right to change the specification without notice, in order to improve the design and supply the best possible product.
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Notes

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3. For data sheets describing multiple type numbers, the highest-level product status determines the data sheet status.

DEFINITIONS

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Limiting values definition — Limiting values given are in accordance with the Absolute Maximum Rating System (IEC 60134). Stress above one or more of the limiting values may cause permanent damage to the device. These are stress ratings only and operation of the device at these or at any other conditions above those given in the Characteristics sections of the specification is not implied. Exposure to limiting values for extended periods may affect device reliability.

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